# **PSU Clamp Test Waveforms & Calculations**

April & May 2025

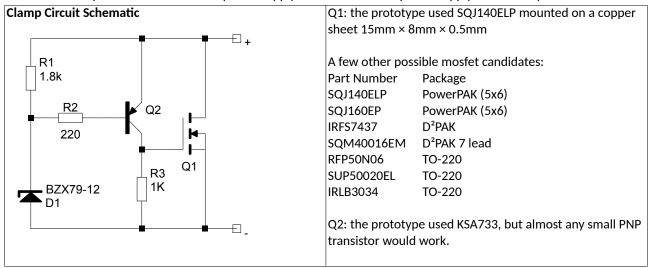
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## Setup

Motor: EMAX ECO 1106, K, = 6000, 12 magnets, with flywheel

Connections: Separate connection from power supply to Remora & from power supply to the clamp circuit



## **Method**

In the ESC32 menu move slider right then left, this rapidly stops the motor sending energy back to the power supply (PSU), as power supplies only source current this raises the PSU voltage. The clamp is designed to start operating at about 12.5V preventing damage to the WiFi and Remora.

```
ESCape32 rev11 [MA_1]
Temp: 19C
Volt: 0.00V
Curr: 0.00A
Csum: 0mAh
ERPM: 186335
```

(slide right and left to arm)

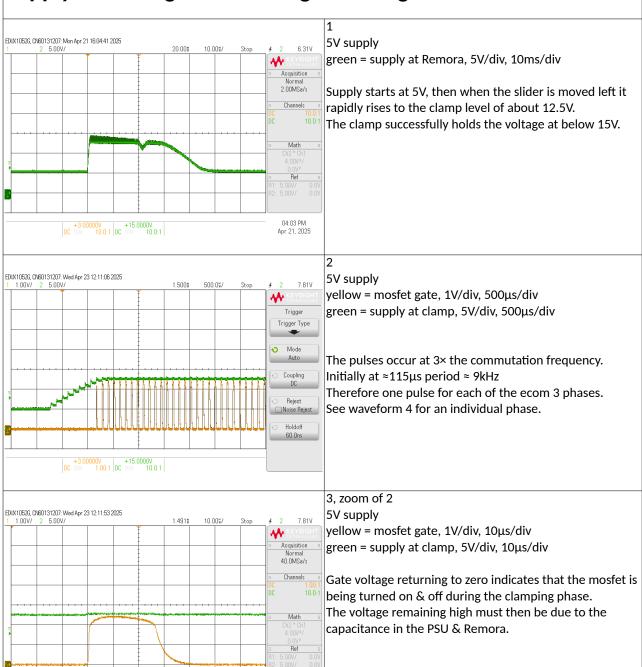
ERPM = rpm × pole pairs  $\therefore$  rpm = ERPM ÷ pole pairs  $\therefore$  rpm = 186335 ÷ 6 = 31056rpm

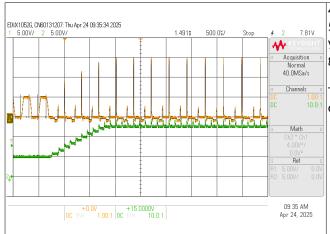
From Kv value: rpm ≈ 5V × 6000Ky = 30000rpm, so in reasonable agreement with ERPM reading from ESC32.

Commutation frequency, Fc = (rpm / 60) × pole pairs = ERPM / 60 = 186335/60 = 3106Hz

Measured Fc from oscilloscope is 3003Hz







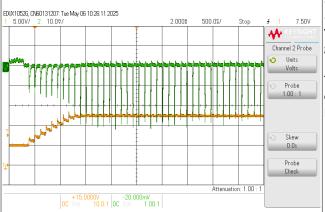
5V supply

yellow = ecom V phase output, 5V/div, 500μs/div green = supply at Remora, 5V/div, 500μs/div

The high amplitude (>10V) spikes on V-phase occur at the commutation frequency.

### currents

(Remora settings slightly different to those for voltage measurements above, running at slightly higher rpm)

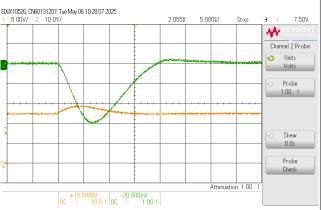


5V supply

yellow = supply at Remora, 5V/div, 500μs/div green = current in Remora +ve line, 2A/div, 500μs/div

The spikes occur at 3× the commutation frequency, i.e. one for each phase.

Initially at ~ 110µs period



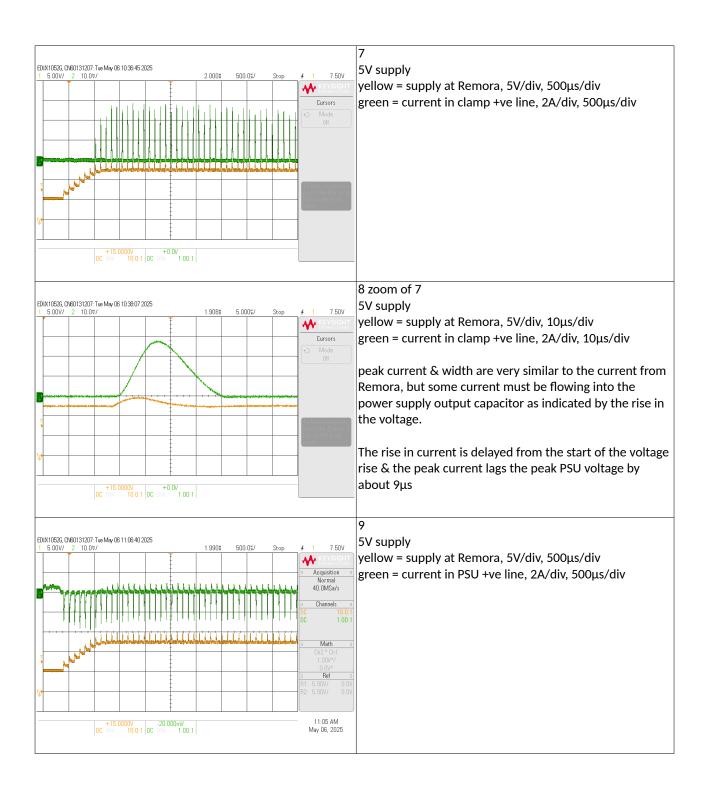
6 zoom of 5

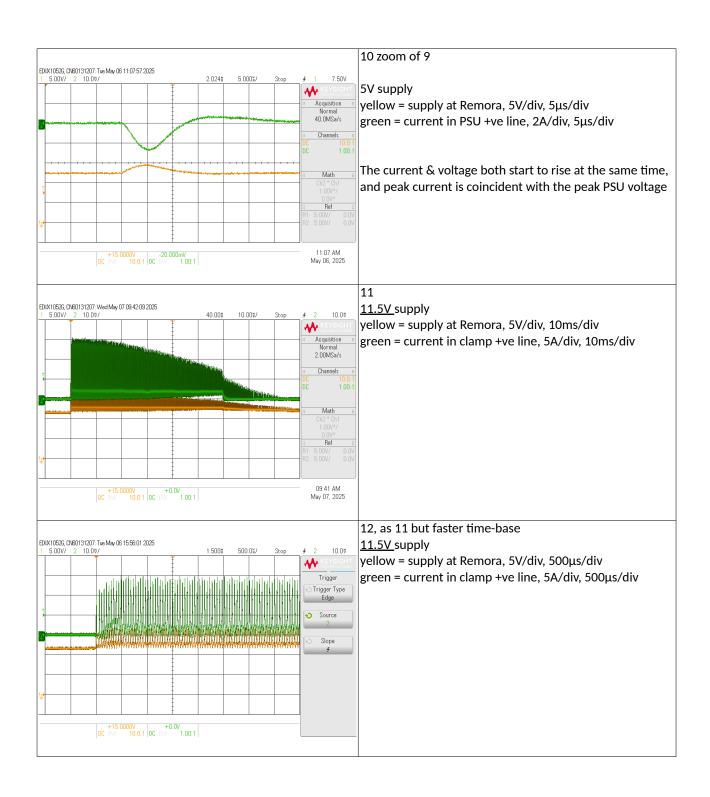
5V supply

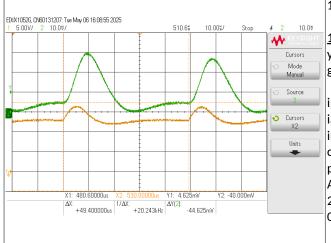
yellow = supply at Remora, 5V/div, 5µs/div green = current in Remora +ve line, 2A/div, 5µs/div

6A peak current fed from Remora to PSU & clamp circuit. Approximately a triangular shape width 20μs So average current ≈ 6A ÷2 × 40μs ÷ 110μs = 1.1A

The current & voltage both start to rise at the same time, but peak current is lags the peak PSU voltage by about 6.8µs







13 zoom of 12

### **11.5V** supply

yellow = supply at Remora, 5V/div, 10µs/div green = current in clamp +ve line, 5A/div, 10µs/div

ipk = 14.5A

iav from scope measurement =4.22A irms from scope measurement = 6.1A current prior to steep rise = 2.3A

period = 49.4µs

Approximately a triangular shape width = 23μs 2.3A step width = 9.4μs 0A to 2.3A ramp width = 10μs

check on iav:

lav  $\approx$  [(14.5÷2×23 $\mu$ s)+ (2.3÷2×10 $\mu$ s) + (2.3×9.4 $\mu$ s)]÷ 49.4 $\mu$ s = 4A, in reasonable agreement with scope measurement.

Vpk = 16.5V Vav = 13.25V

so power =  $13.25V \times 4.22A = 56W$  scope maths = 55W

From waveform 11 duration ≈ 60ms so energy = 3.36J

# Mosfet Safe Operating Area (SOA) & Thermal considerations

### Mosfet SOA

Using IRLB3034 as an example of an SOA chart, because used it in the thermal calculation example below

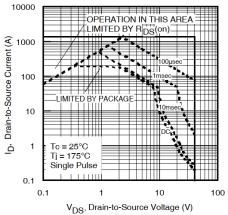


Fig 8. Maximum Safe Operating Area

At 11.5V supply the current pulses are about 15A with a triangular shape of width 23 $\mu$ s, but to allow a generous safety margin use 30A & 50 $\mu$ s. SOA data usually has plots of curves at 100 $\mu$ s so use this instead of 50 $\mu$ s giving an even greater safety margin. The voltage for the SOA will be 15V.

Taking the IRLB3034 SOA as an example its DC SOA at 15V is only about 3A, but its 100µs SOA is about 200A, however this is for a temperature rise of 150°C from 25°C to 175°C. For a good lifetime better to restrict the temperature rise to 75°C so therefore the 100µs SOA current would be reduced to 100A.

This is still in excess of our requirement of 30A so is OK. The actual temperature rise for the 15A 23µs triangular pulse will be very considerably lower than 75°C.

#### Thermal calculations

just to get an estimate of whether a heatsink is required or m = mass kg

thermal energy formula:  $Q = m \times c \times \Delta t$ 

Q = energy J

c = specific heat capacity  $J / kg \cdot K$ 

 $\Delta t = temperature rise K (or °C)$ 

If the energy was dumped in an aluminium heatsink specific heat capacity = 900 J / kg · K allow 20K temperature rise for the aluminium ∴ mass = 0.19g

If the energy was dumped in a copper sheet specific heat capacity = 385 J / kg · K allow 20K temperature rise for the copper sheet ∴ mass = 0.44g

For reference the total mass of a TO-220 is about 1.9g, so it may be able to absorb the energy without an additional heatsink.

#### Thermal simulation model

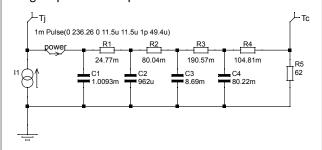
Using IRLB3034 in a TO-220 package as an example. Because it has a thermal model on the data-sheet. (Although it only has a moderate DC SOA its pulse SOA is acceptable).

Triangular power pulses applied with 55W average, see waveform 13.

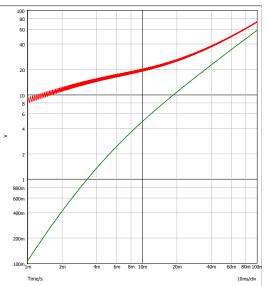
R5 with a thermal resistance of 62K/W represents a TO-220 without a heatsink.

In the model:

current represents thermal power voltage represents temperature



### IRLB3034 thermal model results



Red = junction temperature rise at 60ms, average = 50°C & temperature ripple due to the individual triangular power pulse is small at about 2°C.

green = TO-220 case temperature rise, at 60ms = 35°C

So a TO-220 package without a heatsink has an acceptable temperature rise for a single 60ms burst of pulses, even with an 11.5V supply.